

## General Description

The GreenMOS® high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

The GreenMOS® Generic series is optimized for extreme switching performance to minimize switching loss. It is tailored for high power density applications to meet the highest efficiency standards.

## Features

- Low  $R_{DS(ON)}$  & FOM
- Extremely low switching loss
- Excellent stability and uniformity



## Applications

- PC power
- LED lighting
- Telecom power
- Server power
- EV Charger
- Solar/UPS

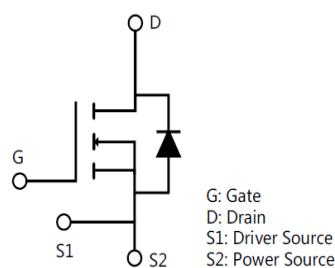
## Key Performance Parameters

Parameter	Value	Unit
$V_{DS}$	650	V
$I_D$ , pulse	330	A
$R_{DS(ON)}$ , max @ $V_{GS}=10V$	20	mΩ
$Q_g$	163	nC

## Marking Information

Product Name	Package	Marking
OSG65R020H4T3F	TO247-4L	OSG65R020H4T3

## Package & Pin Information



**Absolute Maximum Ratings** at  $T_j=25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	$V_{DS}$	650	V
Gate-source voltage	$V_{GS}$	$\pm 30$	V
Continuous drain current <sup>1)</sup> , $T_C=25\text{ }^\circ\text{C}$	$I_D$	110	A
Continuous drain current <sup>1)</sup> , $T_C=100\text{ }^\circ\text{C}$		70	
Pulsed drain current <sup>2)</sup> , $T_C=25\text{ }^\circ\text{C}$	$I_{D,\text{pulse}}$	330	A
Continuous diode forward current <sup>1)</sup> , $T_C=25\text{ }^\circ\text{C}$	$I_S$	110	A
Diode pulsed current <sup>2)</sup> , $T_C=25\text{ }^\circ\text{C}$	$I_{S,\text{pulse}}$	330	A
Power dissipation <sup>3)</sup> , $T_C=25\text{ }^\circ\text{C}$	$P_D$	637	W
Single pulsed avalanche energy <sup>4)</sup>	$E_{AS}$	1800	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0\ldots 480\text{ V}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0\ldots 480\text{ V}$ , $I_{SD}\leq I_D$	dv/dt	15	V/ns
Operation and storage temperature	$T_{stg}, T_j$	-55 to 150	$^\circ\text{C}$

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	0.2	$^\circ\text{C/W}$
Thermal resistance, junction-ambient	$R_{\theta JA}$	62	$^\circ\text{C/W}$

**Electrical Characteristics** at  $T_j=25^\circ\text{C}$  unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	$BV_{DSS}$	650			V	$V_{GS}=0\text{ V}$ , $I_D=2\text{ mA}$
Gate threshold voltage	$V_{GS(\text{th})}$	3.5		4.5	V	$V_{DS}=V_{GS}$ , $I_D=2\text{ mA}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		18	20	$\text{m}\Omega$	$V_{GS}=10\text{ V}$ , $I_D=55\text{ A}$
Gate-source leakage current	$I_{GSS}$			100	nA	$V_{GS}=30\text{ V}$
				-100		$V_{GS}=-30\text{ V}$
Drain-source leakage current	$I_{DS}$			1	$\mu\text{A}$	$V_{DS}=650\text{ V}$ , $V_{GS}=0\text{ V}$
Gate resistance	$R_G$		3.7		$\Omega$	$f=1\text{ MHz}$ , Open drain

### Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C <sub>iss</sub>		10461		pF	V <sub>GS</sub> =0 V, V <sub>DS</sub> =50 V, f=100 kHz
Output capacitance	C <sub>oss</sub>		495		pF	
Reverse transfer capacitance	C <sub>rss</sub>		5.3		pF	
Effective output capacitance, energy related	C <sub>o(er)</sub>		321		pF	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 0V-400V
Effective output capacitance, time related	C <sub>o(tr)</sub>		1934		pF	
Turn-on delay time	t <sub>d(on)</sub>		40.8		ns	V <sub>GS</sub> =10 V, V <sub>DS</sub> =400 V, R <sub>G</sub> =2 Ω, I <sub>D</sub> =50 A
Rise time	t <sub>r</sub>		22		ns	
Turn-off delay time	t <sub>d(off)</sub>		119.2		ns	
Fall time	t <sub>f</sub>		3		ns	

### Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q <sub>g</sub>		163		nC	V <sub>GS</sub> =10 V, V <sub>DS</sub> =400 V, I <sub>D</sub> =50 A
Gate-source charge	Q <sub>gs</sub>		53.6		nC	
Gate-drain charge	Q <sub>gd</sub>		41		nC	
Gate plateau voltage	V <sub>plateau</sub>		5.9		V	

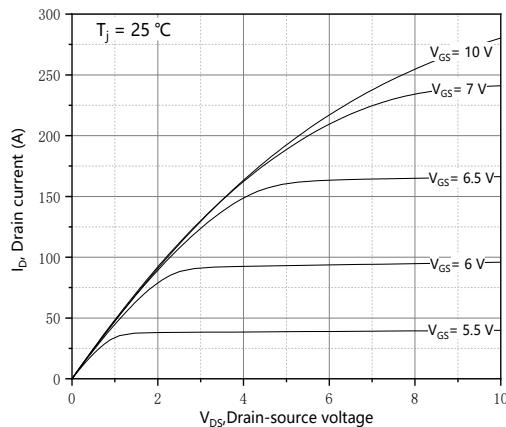
### Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V <sub>SD</sub>			1.3	V	I <sub>S</sub> =110 A, V <sub>GS</sub> =0 V
Reverse recovery time	t <sub>rr</sub>		580		ns	
Reverse recovery charge	Q <sub>rr</sub>		11		μC	
Peak reverse recovery current	I <sub>rrm</sub>		33.6		A	

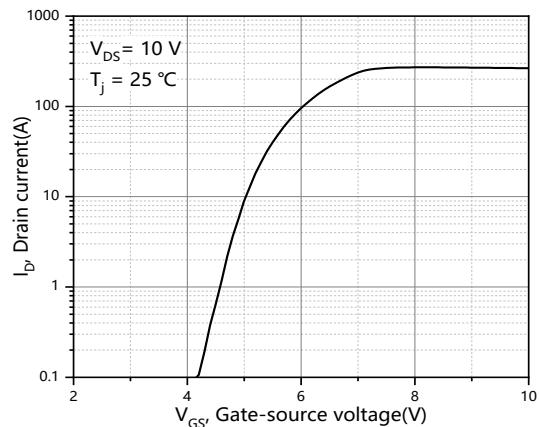
### Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) V<sub>DD</sub>=100 V, V<sub>GS</sub>=10 V, L=80 mH, starting T<sub>j</sub>=25 °C.

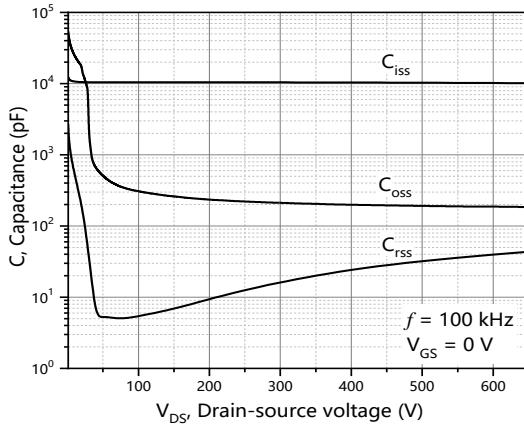
## Electrical Characteristics Diagrams



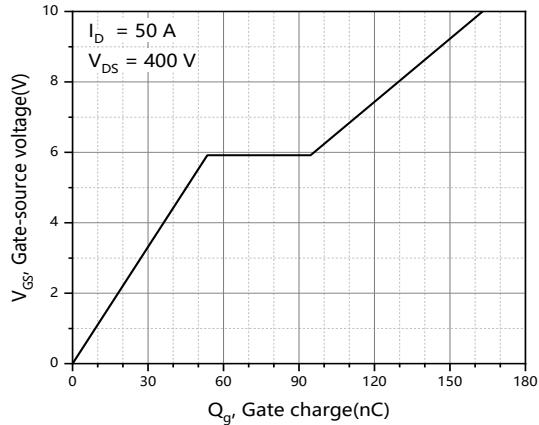
**Figure 1. Typ. output characteristics**



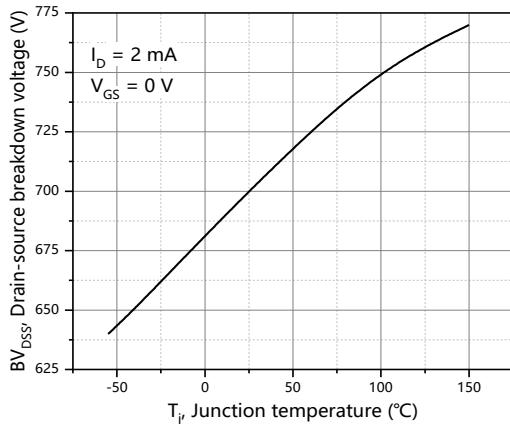
**Figure 2. Typ. transfer characteristics**



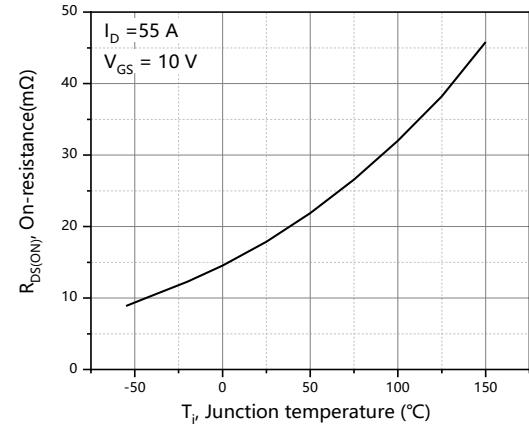
**Figure 3. Typ. capacitances**



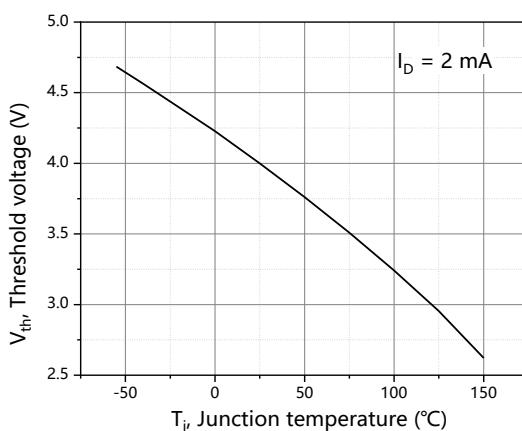
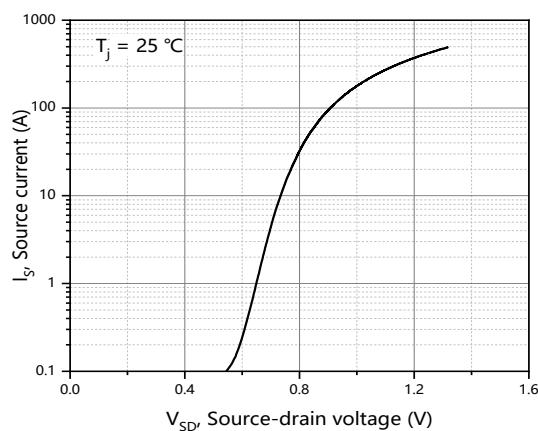
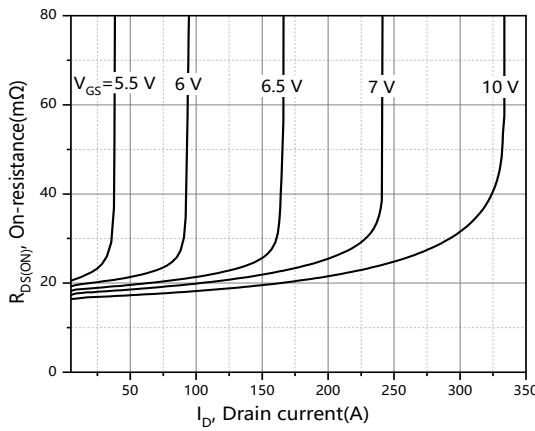
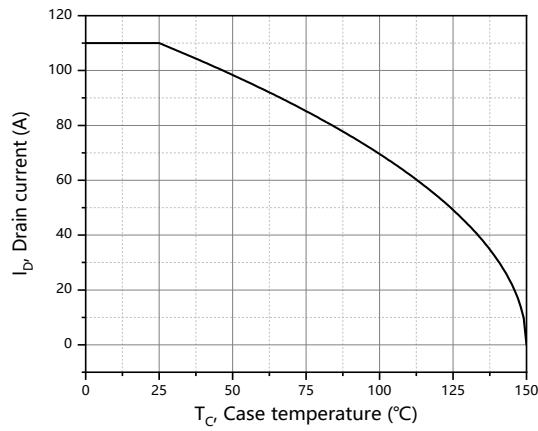
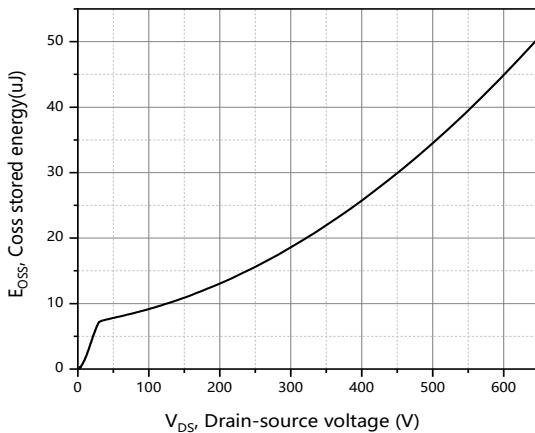
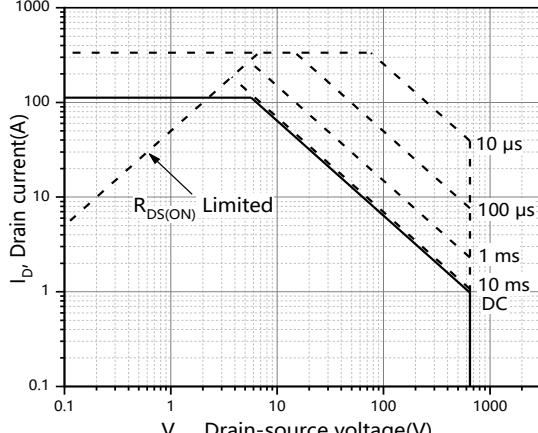
**Figure 4. Typ. gate charge**



**Figure 5. Drain-source breakdown voltage**



**Figure 6. Drain-source on-state resistance**


**Figure 7. Threshold voltage**

**Figure 8. Forward characteristic of body diode**

**Figure 9. Drain-source on-state resistance**

**Figure 10. Drain current**

**Figure 11. Typ. Coss stored energy**

**Figure 12. Safe operation area for  $T_c=25^\circ\text{C}$**

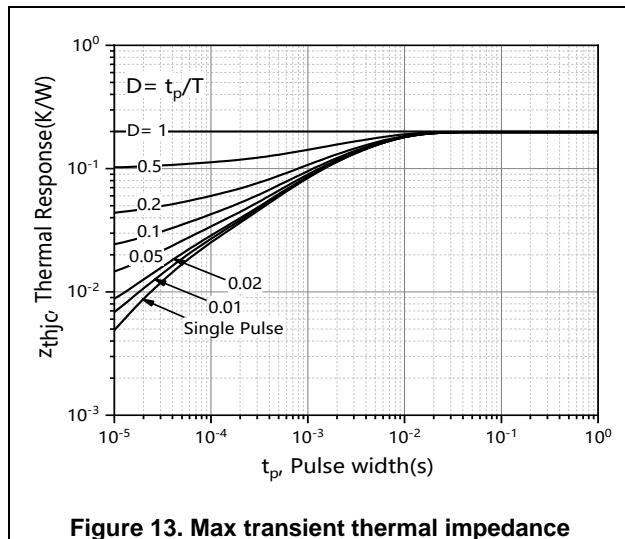
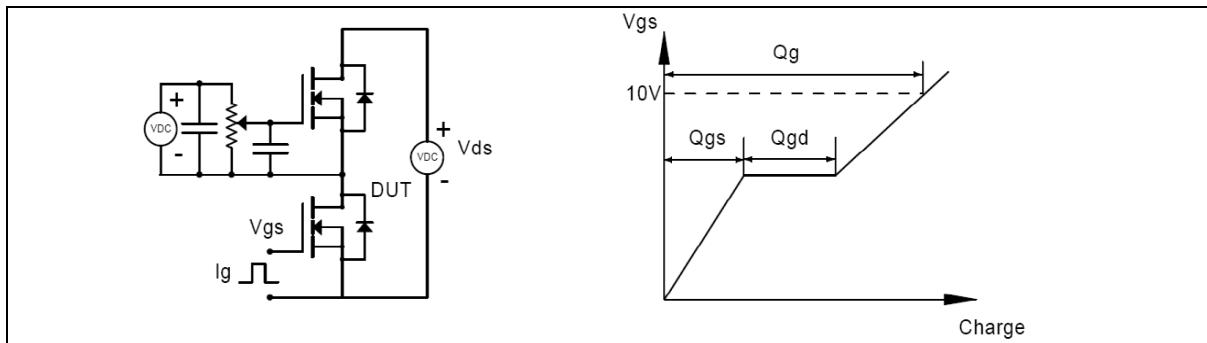
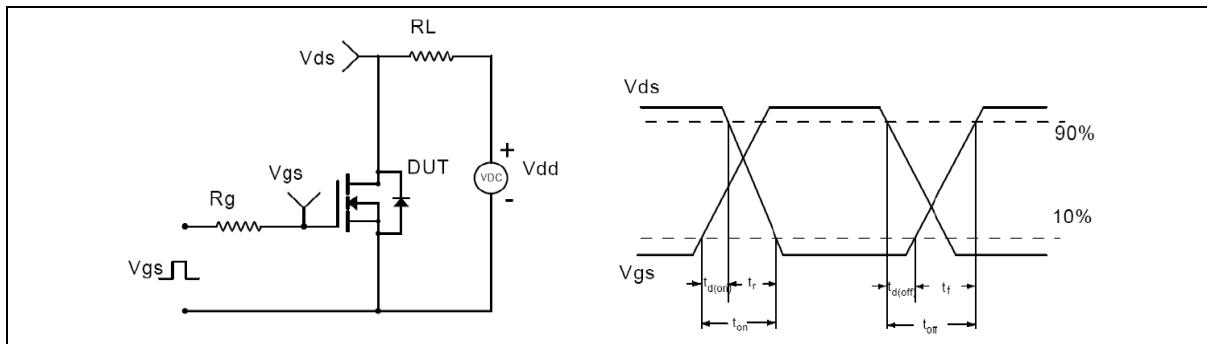


Figure 13. Max transient thermal impedance

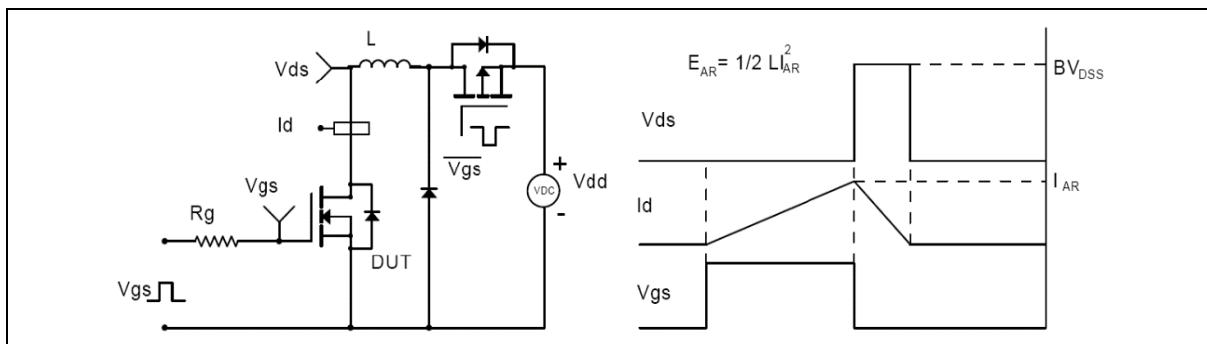
### Test circuits and waveforms



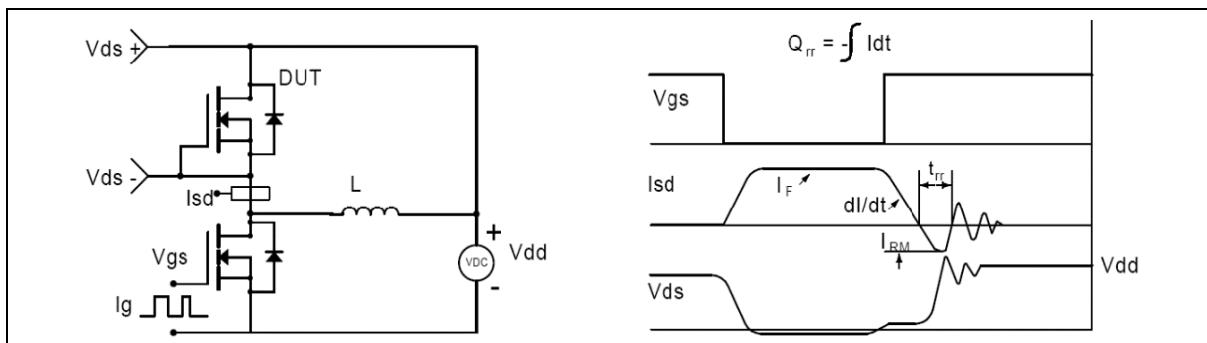
**Figure 1. Gate charge test circuit & waveform**



**Figure 2. Switching time test circuit & waveforms**

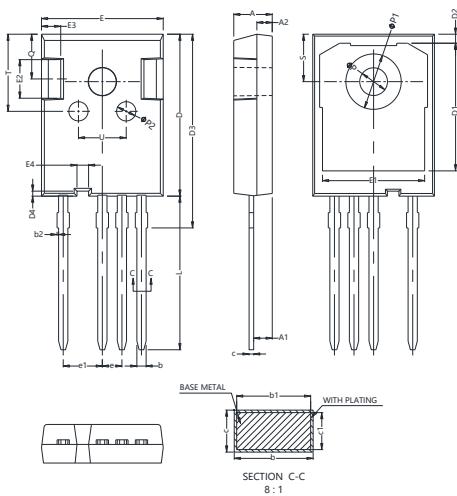


**Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms**



**Figure 4. Diode reverse recovery test circuit & waveforms**

## Package Information



Symbol	mm		
	Min	Nom	Max
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
b	1.16		1.29
b1	1.15	1.2	1.25
b2	0.00		0.20
c	0.59		0.66
c1	0.58	0.60	0.62
D	20.90	21.00	21.10
D1	16.25	16.55	16.85
D2	1.05	1.20	1.35
D3	24.97	25.12	25.27
D4	0.55	0.65	0.75
E	15.70	15.80	15.90
E1	13.10	13.30	13.50
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
E4	1.40	1.50	1.60
e	2.44	2.54	2.64
e1	4.98	5.08	5.18
L	19.80	19.92	20.10
P	3.50	3.60	3.70
P1			7.40
P2	2.40	2.50	2.60
Q	5.60		6.00
S	6.15BSC		
T	9.80		10.20
U	6.00		6.40

Version 1: TO247-4L-J package outline dimension

## Ordering Information

Package Type	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
TO247-4L-J	30	20	600	4	2400

## Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG65R020H4T3F	TO247-4L	yes	yes	yes

## Legal Disclaimer

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Oriental Semiconductor hereby disclaims any and all warranties and liabilities of any kind, including without limitation, warranties of non-infringement of intellectual property rights of any third party.

For further information on technology, delivery terms and conditions and prices, please contact the Oriental Semiconductor sales representatives ([www.orientalsemi.com](http://www.orientalsemi.com)).

© Oriental Semiconductor Co.,Ltd. All Rights Reserved /

